

## Galaxy S8 Application processor Package Analysis

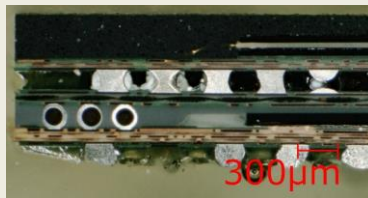
**June, 2018.** LTEC Corporation released the package analysis report of the application processor of Galaxy S8. Galaxy S8 which was released in the 2Q 2017, use two types of application processor depending on the sales area . Qualcomm processor (Snapdragon 835) is used for US and UK market, and Samsung processor (Exynos 8895) is used for other region. In this report, the package structure difference between Sanpdragon 835 and Exynos 8895we is clarified.



Packager top view  
Snapdragon835



Cross section



Cross section



Package top view  
Exynos8895

The both packages consist of two stacked dies, two substrate pcb, and embedded passive components into package. Even though there are several differences between two packages.

The 37-page report includes package images, size measurement, X-ray images, each layers of substrate and cross section details.

Note: The listed report price may not be accurate as it decreases over time.

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